

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDF163AN F11 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_ 2006-5-11 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited

## 更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

**1. SCOPE**

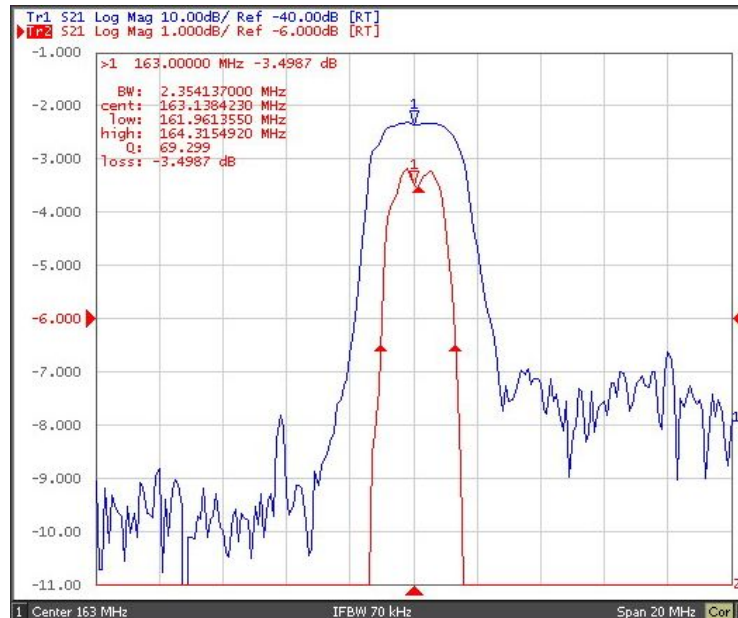
This specification shall cover the characteristics of SAW filter With HD163AN used for the page system.

**2. ELECTRICAL SPECIFICATION**

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

Electronic Characteristics

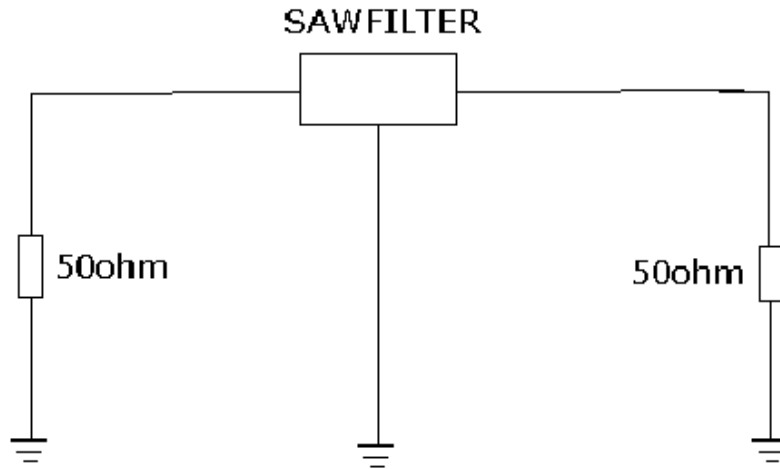
2-1. Typical frequency response



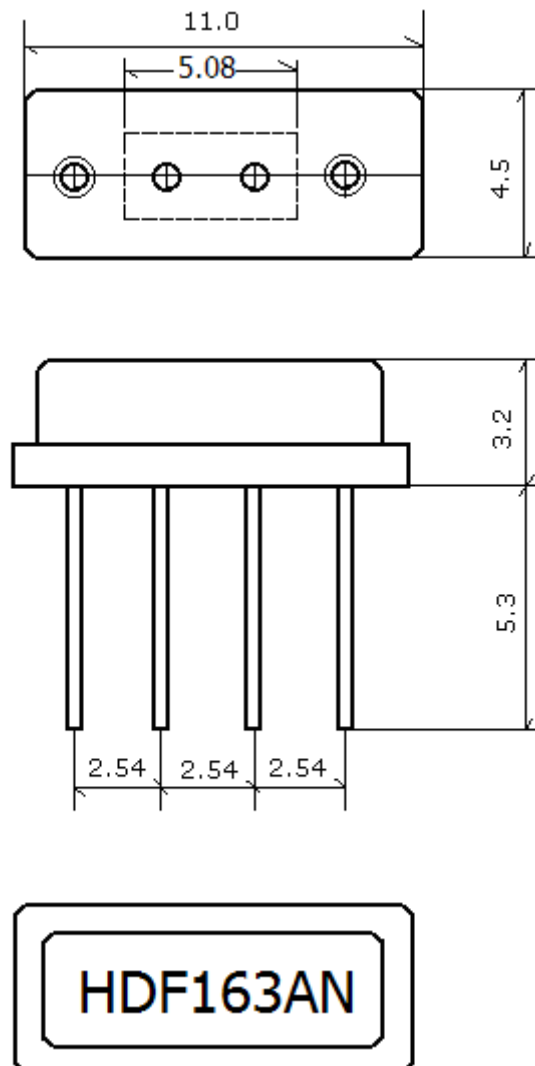
2-2. Electrical characteristics

PART NUMBER	HDF163AN	UNIT
NOMINAL CENTERFREQUENCY(Fo)	163	MHz
INSERTION LOSS:		
1. Fo-100MHz TO Fo -39.5MHz	45.0Min	dB
2. Fo-39.5MHz TO Fo-10.7MHz	40.0 Min	
3. Fo±1.5 MHz	6.0 Max	
4. Fo+10.7MHz TO Fo+39.5MHz	40.0Min	
5. Fo+39.5 TO +100MHz	45.0 Min	
RIPPLE (WITH PASSBAND)	2.0 Max	dB
INPUT AND OUTPUT IMPEDANCE	50/0	Ω /pF

### 3. TEST CIRCUIT



### 4. DIMENSION



## **5. ENVIRONMENTAL CHARACTERISTICS**

### **5-1 Temperature cycling**

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+25^{\circ}\text{C}$  for 5 Minutes and a higher temperature of  $+85^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2-2.

### **5-2 Resistance to solder heat**

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2-2.

### **5-3 Solderability**

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2-2.

### **5-4 Mechanical shock**

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 2-2.

### **5-5 Vibration**

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2-2.

## **6. REMARK**

### **6.1 Static voltage**

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### **6.2 Ultrasonic cleaning**

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### **6.3 Soldering**

Only leads of component may be soldered. Please avoid soldering another part of component.